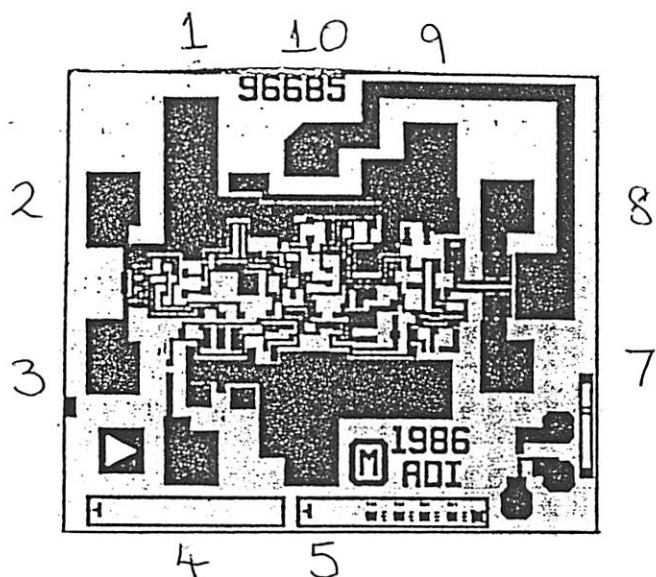


DIE TECHNOLOGY LIMITED



Pad Function

- 1 V_{s+}
- 2 Noninverting Input
- 3 Inverting Input
- 4 Latch Enable
- 5 V_{s-}
- 6 NC
- 7 Q Output
- 8 Q Output
- 9 GND 2
- 10 GND 1

Note: NC = No Connect

The information on this layout is believed to be correct. No liability for error or omission can be accepted. The supply of dice to this layout can only be guaranteed if it forms part of a specification, or the chip identification, if below, is requested. Chip back potential is the level at which bulk silicon is maintained by on-chip connection. It is not to be interpreted as a mounting recommendation unless specifically stated above. If no potential is given the chip back should be isolated. Nominal metal thicknesses are based on manufacturer's information.

<p>Approved: <i>[Signature]</i> Date: 13-1-93</p>	<p>Metallisation/Thickness(KA) Top: Al 12 Back: Si</p> <p>Back Potential: V_{s-} Man's. Part No:</p>	<p>Chip Identification Line Source: Mask Ref: 96685 Process: Version: Geometry:</p>
<p>Corbrook Road Chadderton Lancs. OL9 9SD</p> <p>Tel: 061 626 3827 Fax: 061 627 2341</p>	<p>Dimensions (mils.): 50 x 44 x 15</p> <p align="center">ANALOG DEVICES AD96685</p>	<p>Bond Pads: 4 x 4</p> <p align="right">Issue 1</p>